

PRELIMINARY AMENDMENT

New U.S. Patent Application to Katsuhiko TAKAHASHI et al.

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (original): A conductive composition comprising a particulate silver compound and a binder.

2. (original): A conductive composition comprising a particulate silver compound, a reducing agent and a binder.

3. (currently amended): TheA conductive composition according to either ~~one of~~ claim 1 ~~and~~or claim 2, wherein said particulate silver compound is one or more of silver oxide, silver carbonate and silver acetate.

4. (currently amended): TheA conductive composition according to ~~any one of~~either claim 1 ~~through~~or claim 32, wherein an average particle diameter of said particulate silver compound is within a range from 0.01 to 10 μm .

5. (currently amended): TheA conductive composition according to ~~any one of~~either claim 1 ~~through~~or claim [4]2, wherein said binder is one or more materials selected from a group consisting of polyvalent phenol compounds, phenol resins, alkyd resins, polyester resins and epoxy resins.

6. (currently amended): TheA conductive composition according to ~~any one of~~either claim 1 ~~through~~or claim 52, wherein said binder exhibits a reducing action.

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7. (currently amended): TheA conductive composition according to ~~any one of either~~ claim 1 ~~through~~ claim 42, wherein said binder is a fine powder of a thermoplastic resin with an average particle diameter within a range from 20 nm to 5 μ m.

8. (currently amended): TheA conductive composition according to claim 7, wherein said thermoplastic resin is polystyrene or polyethylene terephthalate.

9. (currently amended): TheA conductive composition according to ~~any one of~~ claim 2 ~~through claim 8~~, wherein said reducing agent is one or more of ethylene glycol, diethylene glycol, triethylene glycol and ethylene glycol diacetate.

10. (currently amended): TheA conductive composition according to ~~any one of either~~ claim 1 ~~through~~ claim 92, having a viscosity within a range from 30 to 300 dPa·sec.

11. (currently amended): A method of forming a conductive coating comprising the steps of applying and then heating a conductive composition according to ~~any one of either~~ claim 1 ~~through~~ claim 102.

12. (currently amended): TheA method of forming a conductive coating according to claim 11 wherein a heating temperature is within a range from 140 to 200°C.

13. (currently amended): A conductive coating, produced by a formation method according to ~~either one of claim 11 and claim 12~~, wherein silver particles are fused together.

14. (currently amended): TheA conductive coating according to claim 13, having a volume resistivity of ~~no more than~~ $3.0 \times 10^{-5} \Omega \cdot \text{cm}$ or less.